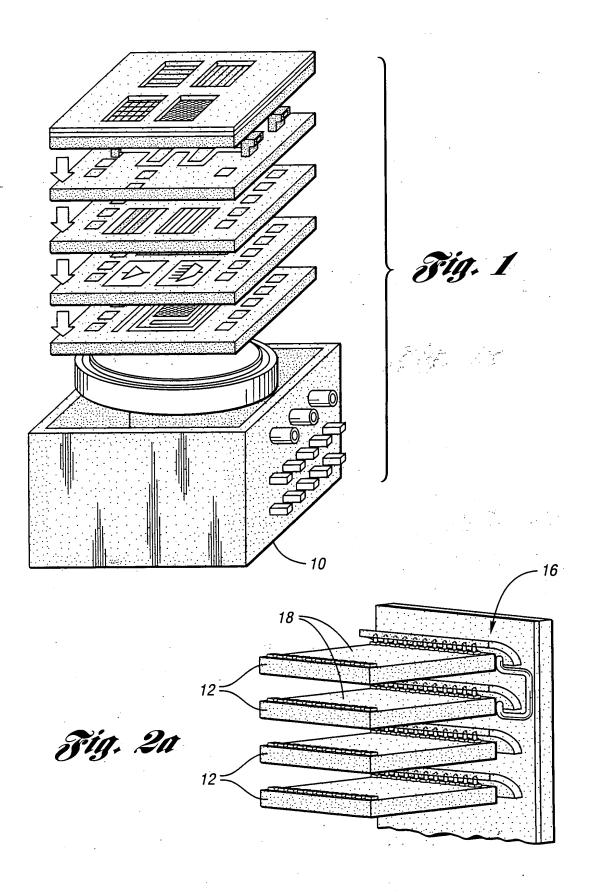
Title: Multi-Substrate Package and Method For Assembling Same
First Named Inventor:
plication Serial No.: / Atty. Docket No.: UOM 0319 PUS

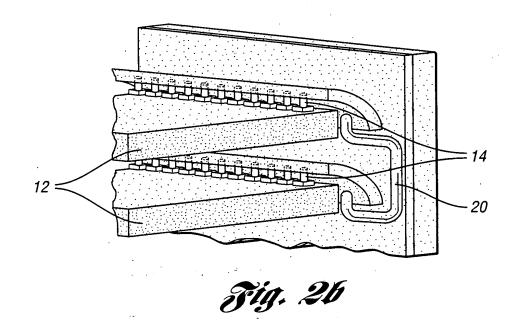
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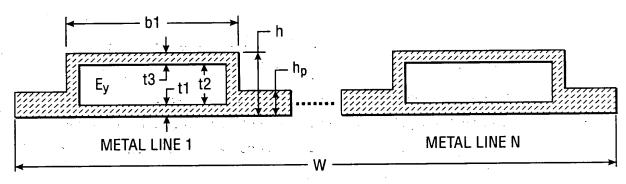


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First Named Inventor:
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Application Serial No.:

2/6







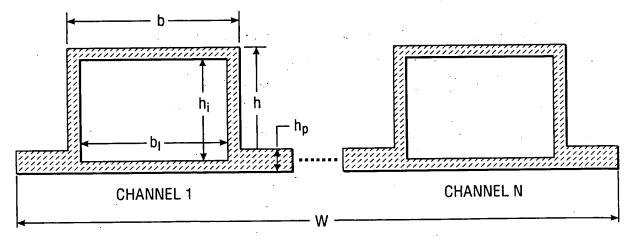
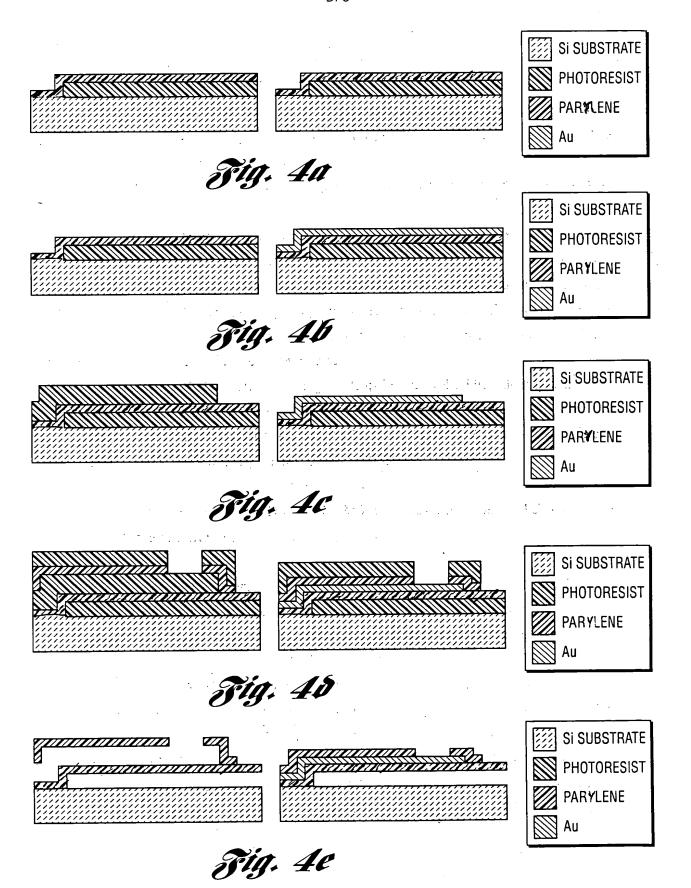


Fig. 36

Title: Multi-Substrate Package and Method For Assembling Same First Named Inventor:

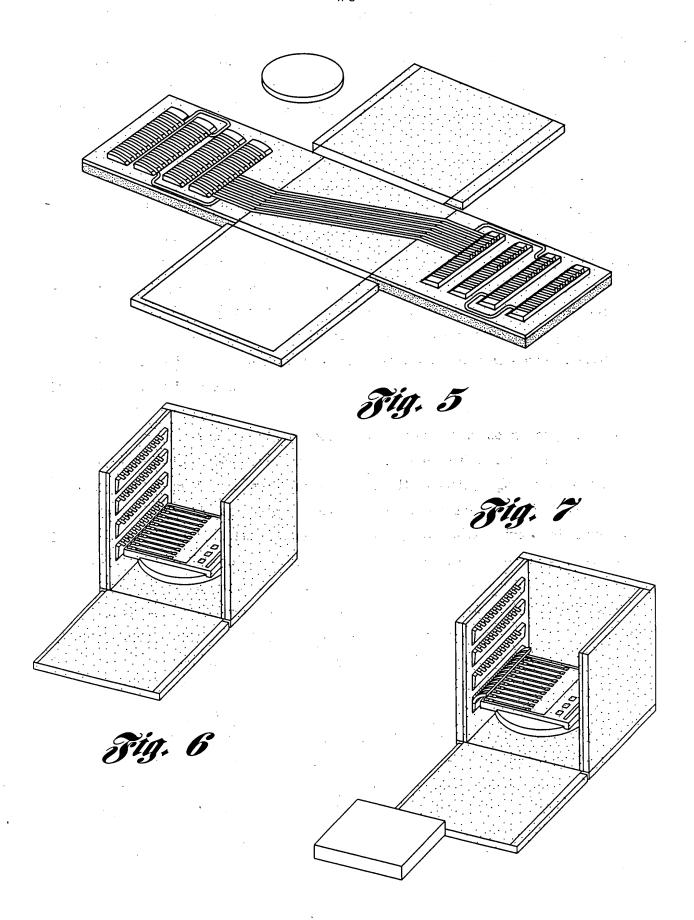
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/ Atty. Docket No.: UOM 0319 PUS



Title: Multi-Substrate Package and Method For Assembling Same
First Named Inventor:
plication Serial No.: / Atty. Docket No.: UOM 0319 PUS

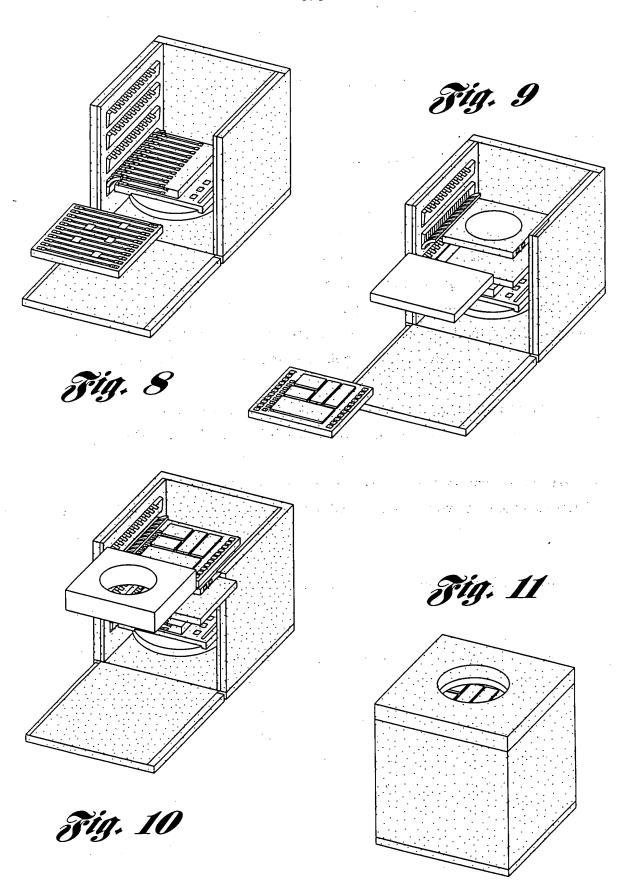
Application Serial No.:



Title: Multi-Substrate Package and Method For Assembling Same First Named Inventor:

Application Serial No.:

/ Atty. Docket No.: UOM 0319 PUS

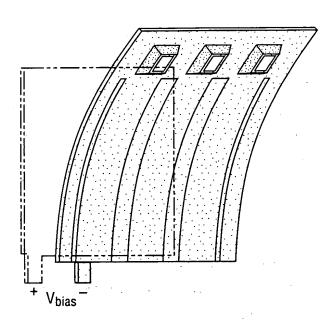


Title: Multi-Substrate Package and Method For Assembling Same First Named Inventor:

Application Serial No.:

/ Atty. Docket No.: UOM 0319 PUS

6/6



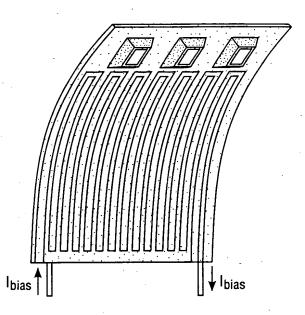
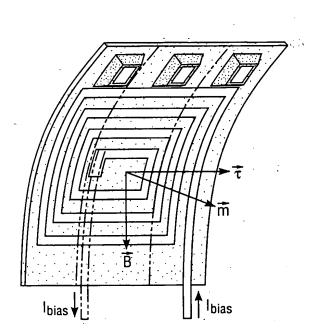


Fig. 12

Fig. 13





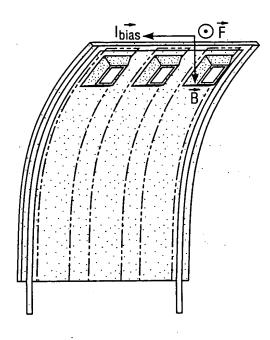


Fig. 15